

MOS INTEGRATED CIRCUIT $\mu PD16717$

384-OUTPUT TFT-LCD SOURCE DRIVER (COMPATIBLE WITH 64-GRAY SCALES)

DESCRIPTION

The μ PD16717 is a source driver for TFT-LCDs capable of dealing with displays with 64-gray scales. Data input is based on digital input configured as 6 bits by 6 dots (2 pixels), which can realize a full-color display of 260,000 colors by output of 64 values γ -corrected by an internal D/A converter and 5-by-2 external power modules. Because the output dynamic range is as large as Vss₂ + 0.2 V to V_{DD2} – 0.2 V, level inversion operation of the LCD's common electrode is rendered unnecessary. Also, to be able to deal with dot-line inversion, n-line inversion and column line inversion when mounted on a single side, this source driver is equipped with a built-in 6-bit D/A converter circuit whose odd output pins and even output pins respectively output gray scale voltages of differing polarity. Assuring a maximum clock frequency of 55 MHz when driving at 2.5 V, this driver is applicable to XGA-standard TFT-LCD panels and SXGA TFT-LCD panels.

FEATURES

- CMOS level input (2.5 to 3.6 V)
- 384 outputs
- Input of 6 bits (gray-scale data) by 6 dots
- Capable of outputting 64 values by means of 5-by-2 external power modules (10 units) and a D/A converter (R-DAC)
- Logic power supply voltage (VDD1): 2.5 to 3.6 V
- Driver power supply voltage (V_DD2): 8.5 V \pm 0.5 V
- High-speed data transfer: fcLK = 55 MHz (internal data transfer speed when operating at VDD1 = 2.5 V)
- Output dynamic range: Vss2 + 0.2 V to VDD2 0.2 V
- Apply for dot-line inversion, n-line inversion and column line inversion
- Output voltage polarity inversion function (POL)
- Input data inversion function (POL2)
- Through rate control inversion function (SRC)
- Output reset control inversion function (MODE)
- Slim chip

ORDERING INFORMATION

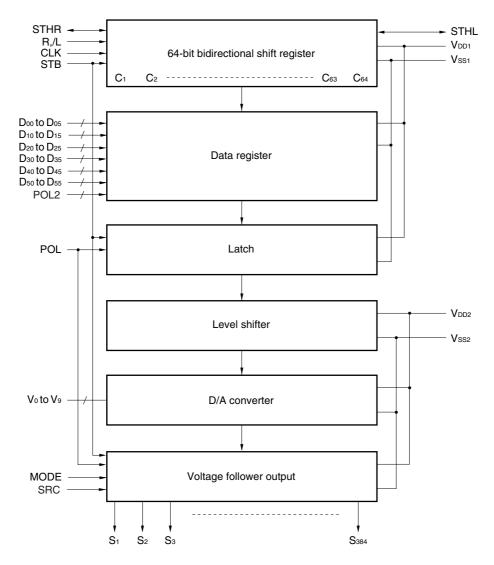
Part NumberPackageμ PD16717N-xxxTCP (TAB package)

Remark The TCP's external shape is customized. To order the required shape, so please contact one of our sales representatives.

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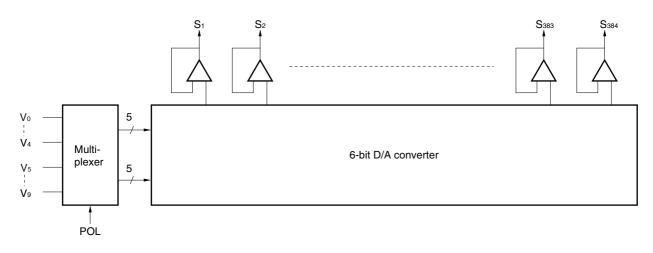
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★ 1. BLOCK DIAGRAM

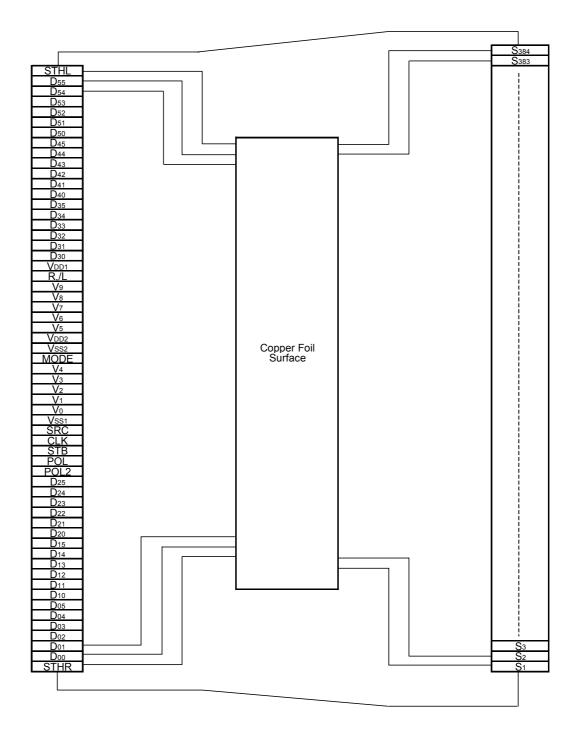


Remark /xxx indicates active low signal.

\star 2. RELATIONSHIP BETWEEN OUTPUT CIRCUIT AND D/A CONVERTER



3. PIN CONFIGURATION (µPD16717) (Copper Foil Surface, Face-up)



Remark This figure does not specify the TCP package.

★ 4. PIN FUNCTIONS

Pin Symbol	Pin Name	I/O	Description
S1 to S384	Driver	Output	The D/A converted 64-gray-scale analog voltage is output.
Doo to Dos	Display data	Input	The display data is input with a width of 36 bits, viz., the gray scale data (6 bits) by 6
D10 to D15			dots (2 pixels).
D20 to D25			Dx0: LSB, Dx5: MSB
D30 to D35			
D40 to D45			
D50 to D55			
R,/L	Shift direction control	Input	These refer to the shift direction control input pins when driver ICs are connected in cascade. The shift directions of the shift registers are as follows. R,/L = H (right shift): STHR (input), S ₁ \rightarrow S ₃₈₄ , STHL (output) R,/L = L (left shift) : STHL (input), S ₃₈₄ \rightarrow S ₁ , STHR (output)
STHR	Right shift start pulse	I/O	These refer to the start pulse I/O pins when driver ICs are connected in cascade. Fetching of display data starts when H is read at the rising edge of CLK. R,/L = H (right shift): STHR input, STHL output
STHL	Left shift start pulse	I/O	R,/L = L (left shift): STHL input, STHR output A high level should be input as the pulse of one cycle of the clock signal. If the start pulse input is more than 2CLK, the first 1CLK of the high-level input is valid.
CLK	Shift clock	Input	Refers to the shift register's shift clock input. The display data is incorporated into the data register at the rising edge. At the rising edge of the 64th after the start pulse input, the start pulse output reaches the high level, thus becoming the start pulse of the next-level driver. If 66th clock pulses are input after input of the start pulse, input of display data is halted automatically. The contents of the shift register are cleared at the STB's rising edge. This pin should not stop during blanking period.
STB	Latch	Input	The contents of the data register are transferred to the latch circuit at the rising edge. Output timing of gray scale voltage is changed by setting MODE. MODE = H or open: STB at the falling edge, the gray scale voltage is supplied to the driver. MODE = L: After set to STB = H, the gray scale voltage is supplied by the rising edge behind 3 clocks. It is necessary to ensure input of one pulse per horizontal period.
POL	Polarity	Input	POL = L: The S _{2n-1} output uses V ₀ to V ₄ as the reference supply. The S _{2n} output uses V ₅ to V ₉ as the reference supply. POL = H: The S _{2n-1} output uses V ₅ to V ₉ as the reference supply. The S _{2n} output uses V ₀ to V ₄ as the reference supply. S _{2n-1} indicates the odd output: and S _{2n} indicates the even output. Input of the POL signal is allowed the setup time (t _{POL-STB}) with respect to STB's rising edge.
POL2	Data inversion	Input	Data inversion can invert when display data is loaded. POL2 = H: Data inversion inverts display data inside IC. POL2 = L: Data inversion does not invert input data. When in STB = H, it becomes test mode if POL2 is changed, throughout STB = H period should not carry out the change of POL2.

			(2/2)
Pin Symbol	Pin Name	I/O	Description
MODE	Output reset control	Input	MODE = H or open: Output reset. STB at the falling edge, the gray scale voltage is supplied to the driver.
			MODE = L: Non-output reset. After set to STB = H, the gray scale voltage is supplied by the rising edge behind 3 clocks.
			This pin is pulled up to the VDD2 power supply inside the IC.
SRC	High driving time	Input	This pin is set up to high drive time by the multiple of STB width.
	control		SRC = H or open: High drive time is twice the STB width.
			SRC = L: High drive time is three times the STB width.
			Refer to 9. SRC PIN AND HIGH DRIVING TIME
			This pin is pulled up to the VDD1 power supply inside the IC.
Vo to V9	γ -corrected power	_	Input the γ -corrected power supplies from outside by using operational amplifier.
	supplies		Make sure to maintain the following relationships. During the gray scale voltage output,
			be sure to keep the gray scale level power supply at a constant level.
			$V_{DD2} - 0.2 \ V \ge V_0 > V_1 > V_2 > V_3 > V_4 \ge 0.5 \ V_{DD2}$
			$0.5 \ V_{DD2} \ge V_5 > V_6 > V_7 > V_8 > V_9 \ge V_{SS2} + 0.2 \ V$
VDD1	Logic power supply	-	2.5 to 3.6 V
Vdd2	Driver power supply	_	$8.5 V \pm 0.5 V$
Vss1	Logic ground	_	Grounding
Vss2	Driver ground	-	Grounding

- Cautions 1. The power start sequence must be VDD1, logic input, and VDD2 & V0 to V9 in that order. Reverse this sequence to shut down (Simultaneous power application to VDD2 and V0 to V9 is possible.).
 - 2. To stabilize the supply voltage, please be sure to insert a 0.1 μ F bypass capacitor between V_{DD1}-V_{SS1} and V_{DD2}-V_{SS2}. Furthermore, for increased precision of the D/A converter, insertion of a bypass capacitor of about 0.01 μ F is also recommended between the γ -corrected power supply terminals (V₀, V₁, V₂,...., V₉) and V_{SS}.

5. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT VOLTAGE VALUE

The μ PD16717 incorporates a 6-bit D/A converter whose odd output pins and even output pins output respectively gray scale voltages of differing polarity with respect to the LCD's counter electrode voltage. The D/A converter consists of ladder resistors and switches.

The ladder resistors (r0 to r62) are designed so that the ratio of LCD panel γ -compensated voltages to V₀' to V₆₃' and V₀'' to V₆₃'' is almost equivalent. For the 2 sets of five γ -compensated power supplies, V₀ to V₄ and V₅ to V₉, respectively, input gray scale voltages of the same polarity with respect to the common voltage

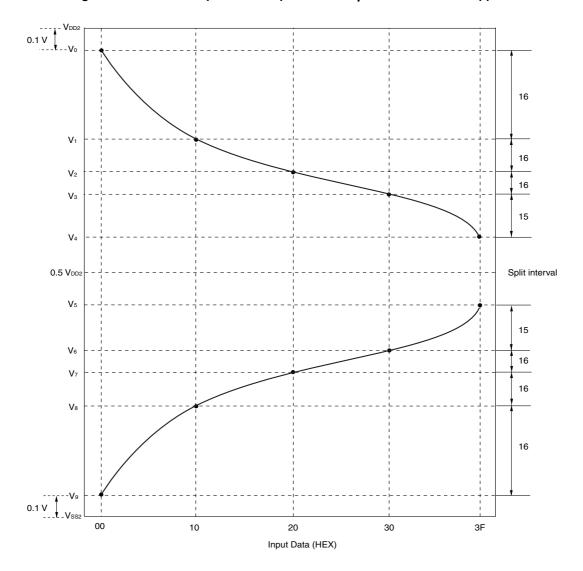
Figure 5–1 shows the relationship between the driving voltages such as liquid-crystal driving voltages V_{DD2} and V_{SS2} , common electrode potential V_{COM} , and γ -corrected voltages V_0 to V_9 and the input data. Be sure to maintain the voltage relationships of

 $V_{\text{DD2}} - 0.2 \ V \geq V_0 > V_1 > V_2 > V_3 > V_4 \geq 0.5 \ V_{\text{DD2}}$

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 $0.5 V_{DD2} \ge V_5 > V_6 > V_7 > V_8 > V_9 \ge V_{SS2} + 0.2 V_{SS2}$

Figures 5–2 and 5–3 indicate the relationship between the input data and output voltage and the resistance values of the resistor string.





Data Sheet S15375EJ1V0DS

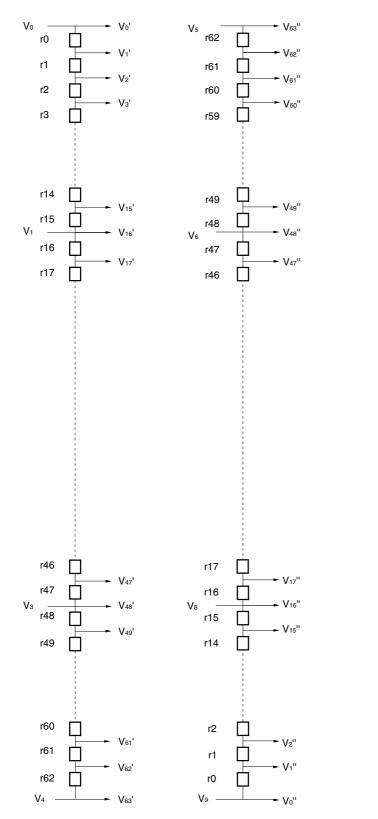


Figure 5–2. γ -corrected Voltages and Ladder Resistors Ratio

r0 6.2 5.8 r1 r2 5.4 5.1 r3 r4 4.7 4.3 r5 4.3 r6 r7 3.9 r8 3.9 3.1 3.1 r9 r10 2.7 r11 r12 2.7 r13 2.3 r14 r15 2.0 r16 r17 1.8 1.8 r18 r19 1.7 r20 1.6 r21 1.5 r22 1.5 14 r23 r24 1.3 r25 1.3 r26 1.2 1.2 r27 r28 1.1 r29 1.1 r30 1.0 1.0 r31 r32 1.0 r33 1.0 r34 1.0 1.0 r35 r36 1.0 r37 1.0 r38 1.0 1.0 r39 r40 1.0 r41 1.0 r42 1.0 r43 1.0 1.0 r44 r45 1.0 r46 1.0 1.0 r47 1.1 r48 r49 1.1 r50 1.1 r51 1.1 1.1 r52 1.6 r53 r54 1.6 1.6 r55 1.6 r56 r57 1.6 r58 2.1 r59 2.7 3.4 r60 5.2 r61 r62 11.2

Ratio

rn

Caution There is no connection between V4 and V5 terminal in the chip.

Data Sheet S15375EJ1V0DS

Figure 5–3. Relationship between Input Data and Output Voltage (POL2 = L)

(Output Voltage 1) VDD2 – 0.2 V \geq V5 > V6 > V7 > V8 > V9 \geq 0.5 VDD2

(Output Voltage 2) 0.5 VDD2 ≥ V5 > V6 > V7 > V8 > V9 ≥ VSS2 + 0.2 V

	•	ilpul v	/oltage 2) 0.		5 - V6 -	V/ -			
	Input Data	V		oltage1		V		oltage2	
				56.4 /	62.6			62 /	62.6
							0 (0 0)		
		-							
	06H	-			62.6			31.5 /	62.6
	07H		$V_1 + (V_0 - V_1) \times$	26.8 /	62.6	V _{7"}	V ₉ +(V ₈ -V ₉)×	35.8 /	
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	08H	V _{8'}	$V_1 + (V_0 - V_1) \times$	22.9 /	62.6	V _{8"}	V ₉ +(V ₈ -V ₉)×	39.7 /	62.6
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$		V _{10'}							
		V _{11'}		-		V _{11"}			
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $									
				2.3 /	02.0			60.3 /	02.0
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $		-		20.7 /	22.6			20 /	22.6
		-							
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$			= (· _,						
$\begin{array}{c c c c c c c c c c c c c c c c c c c $									
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $		V _{23'}						12.0 /	22.6
$ \begin{array}{rrrrrrrrrrrrrrrrrrrrrrrrrrrrrrr$	18H	V _{24'}	$V_2 + (V_1 - V_2) \times$	9.3 /	22.6			13.4 /	22.6
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	19H		$V_2 + (V_1 - V_2) \times$	7.9 /	22.6		V ₈ +(V ₇ -V ₈)×	14.7 /	22.6
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	1AH	V _{26'}	$V_2 + (V_1 - V_2) \times$		22.6	V _{26"}	V ₈ +(V ₇ -V ₈)×	16.0 /	
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	1BH	V _{27'}	$V_2 + (V_1 - V_2) \times$	5.4 /		V _{27"}			
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$									
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$		-							
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$									
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$				1.0 /	22.0	V _{31"}		21.0 /	22.0
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$				15.0 /	16.0			10 /	16.0
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$								-	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $									
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $									
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $								-	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	26H			10.0 /	16.0			6.0 /	16.0
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	27H	V _{39'}	$V_3 + (V_2 - V_3) \times$	9.0 /	16.0	V _{39"}		7.0 /	16.0
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	28H	V _{40'}	$V_3 + (V_2 - V_3) \times$	8.0 /	16.0	V _{40"}		8.0 /	16.0
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	29H	V _{41'}	$V_3 + (V_2 - V_3) \times$	7.0 /		V _{41"}	$V_7 + (V_6 - V_7) \times$	9.0 /	16.0
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	2AH	V _{42'}			16.0	V _{42"}	$V_7 + (V_6 - V_7) \times$	10.0 /	16.0
$\begin{array}{c c c c c c c c c c c c c c c c c c c $									
$\begin{array}{c c c c c c c c c c c c c c c c c c c $									
$\begin{array}{c c c c c c c c c c c c c c c c c c c $						V _{45"}			
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		V _{46'}				V _{46"}			
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		V _{47'}		1.0 /	16.0	V _{47"}		15.0 /	16.0
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		V 48'		367/	37 0			11 /	37 0
$\begin{array}{c c c c c c c c c c c c c c c c c c c $			1 1 0 17						
$\begin{array}{c c c c c c c c c c c c c c c c c c c $							$V_{e} + (V_{e} - V_{e}) \times$		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		-							
$\begin{array}{c c c c c c c c c c c c c c c c c c c $						-			37.8
$\begin{array}{c c c c c c c c c c c c c c c c c c c $									
$\begin{array}{c c c c c c c c c c c c c c c c c c c $									37.8
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	38H			27.7 /	37.8			10.1 /	37.8
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		V ₅₇				V _{57"}			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$							- ()		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$									
3EH V ₆₂ V ₄ +(V ₃ -V ₄)× 11.2 / 37.8 V ₆₂ V ₆ +(V ₅ -V ₆)× 26.6 / 37.8			1 (0 1)						
3⊦H V _{63'} V ₄ V ₅				T1.2 /	31.8			∠0.b /	31.8
	3FH	V _{63'}	V4			V _{63"}	V5		

Caution There is no connection between V4 and V5 terminal in the chip.

6. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT PIN

Data format : 6 bits x 2 RGBs (6 dots) Input width : 36 bits (2-pixel data)

(1) R,/L = H (Right shift)

			<u> </u>	<u> </u>	0	0
Output	S1	S2	S3	S4	 S383	S384
Data	Doo to Do5	D10 to D15	D20 to D25	D30 to D35	 D40 to D45	D50 to D55

(2) R,/L = L (Left shift)

Output	S1	S ₂	S3	S4	 S 383	S384
Data	Doo to Dos	D10 to D15	D20 to D25	D30 to D35	 D40 to D45	D50 to D55

POL	Note S _{2n-1}	Note S _{2n}
L	V_0 to V_4	V5 to V9
Н	V5 to V9	V_0 to V_4

Note S_{2n-1} (Odd output), S_{2n} (Even output)

7. RELATIONSHIP BETWEEN STB, CLK, AND OUTPUT WAVEFORM (MODE =L)

This chapter indicates relationship between STB, CLK, and output waveform in the μ PD16717.

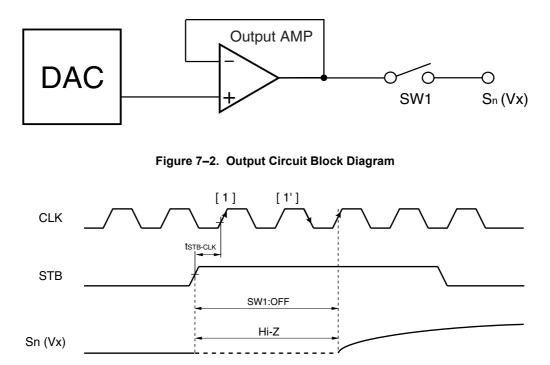
In figure 7–2, STB = H is taken in by the rising edge of CLK [1]. However, when not satisfying the standard of

 $t_{STB-CLK}$, STB = H is taken in by the rising edge of the next CLK [1']. The latch of display data is completed by the falling edge of the next CLK which took in STB = H.

Moreover, synchronizing with the rising edge of the next CLK, driver output is started after the completion of a display data latch.

Therefore, in order to output the gray scale voltage, it is at least 3 clock necessity.

Figure 7–1. Output Circuit Block Diagram



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8. RELATIONSHIP BETWEEN MODE, STB, POL AND OUTPUT WAVEFORM

MODE = H or open:

A total output serves as RESET (short circuit), and throughout STB = H outputs gray scale voltage to the LCD panel synchronizing with the falling edge of STB.

MODE = L:

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This is set to STB = H and a 2 clock cycle all output outputs gray scale voltage to the LCD panel after Hi-Z. Refer to 7. RELATIONSHIP BETWEEN STB, CLK, AND OUTPUT WAVEFORM (MODE = L).

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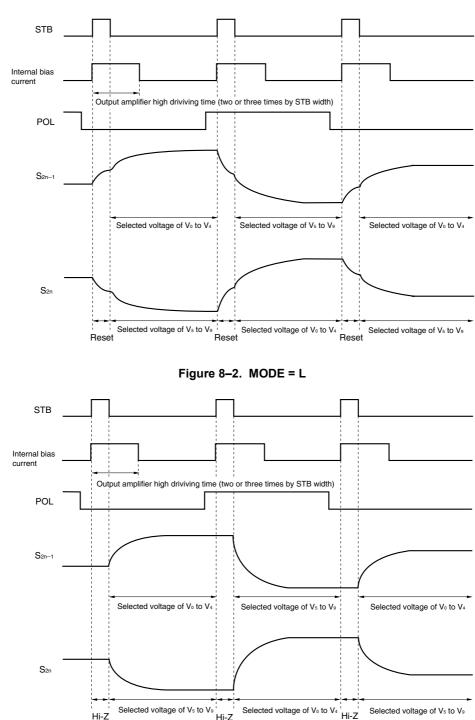


Figure 8–1. MODE = H or open

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Hi-Z

Hi-Z

9. SRC PIN AND HIGH DRIVING TIME

The μ PD16717 has a current consumption of selection or driver IC simple substance is the high drive time of output amplifier controllable by the logic of SRC pin.

SRC = H or open: High drive time is twice the STB width. SRC = L: High drive time is three times the STB width.

High drive time at counting the clock has decided in STB period, and the relationship is as follows. The high drive time of table is the number of clocks from STB falling.

	High driving time					
CLK in STB period	SRC = H or open (unit: CLK)	SRC = L (unit: CLK)				
Under 7CLK	8	16				
8 to 15CLK	16	32				
16 to 23CLK	24	48				
24 to 31CLK	32	64				
32 to 39CLK	40	80				
40 to 47CLK	48	96				
48 to 55CLK	56	112				
56 to 63CLK	64	128				
64 to 71CLK	72	144				
72 to 79CLK	80	160				
80 to 87CLK	88	176				
88 to 95CLK	96	192				
96 to 103CLK	104	208				
104 to 111CLK	112	224				
112CLK or up	Proh	ibited				

Table 9–1. Relationship between Number of Clocks in STB Period and High Drive Time

In consideration of the characteristic of the LCD panel, after the system estimates sufficient, please decide on the high driving time of output amplifier.

10. ELECTRICAL SPECIFICATIONS

Parameter	Symbol	Rating	Unit
Logic Part Supply Voltage	VDD1	-0.5 to +4.0	V
Driver Part Supply Voltage	VDD2	-0.5 to +10.0	V
Logic Part Input Voltage	V _{I1}	-0.5 to V _{DD1} + 0.5	V
Driver Part Input Voltage	V ₁₂	-0.5 to V _{DD2} + 0.5	V
Logic Part Output Voltage	Vo1	-0.5 to V _{DD1} + 0.5	V
Driver Part Output Voltage	V ₀₂	-0.5 to V _{DD2} + 0.5	V
Operating Ambient Temperature	TA	-10 to +75	°C
Storage Temperature	Tstg	–55 to +125	°C

Absolute Maximum Ratings (TA = 25°C, Vss1 = Vss2 = 0 V)

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Logic Part Supply Voltage	V _{DD1}		2.5		3.6	V
Driver Part Supply Voltage	V _{DD2}		8.0	8.5	9.0	V
High-Level Input Voltage	VIH		0.7 VDD1		V _{DD1}	V
Low-Level Input Voltage	VIL		0		0.3 VDD1	V
γ -Corrected Voltage	V ₀ to V ₄		0.5 VDD2		VDD2 - 0.2	V
	V5 to V9		0.2		0.5 VDD2	V
Driver Part Output Voltage	Vo		V _{SS2} + 0.2		VDD2 - 0.2	V
Clock Frequency	fclk				55	MHz

Recommended Operating Range ($T_A = -10$ to $+75^{\circ}C$, $V_{SS1} = V_{SS2} = 0$ V)

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	Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
	Input Leak Current	lı∟	Exclude MODE, SRC			±1.0	μA
*			MODE, SRC			T.B.D.	μA
	High-Level Output Voltage	Vон	STHR (STHL), Іон = 0 mA	VDD1 - 0.1			V
	Low-Level Output Voltage	Vol	STHR (STHL), lo∟ = 0 mA			0.1	V
	γ -Corrected Resistance	Rγ	V_0 to $V_4 = V_5$ to $V_9 = 4.0$ V	9.8	13.8	23.0	kΩ
	Driver Output Current	Ілон	Vx = 7.0 V, Vout = 6.5 V ^{Note}			-300	μA
		IVOL	Vx = 1.0 V, Vout = 1.5 V ^{Note}	300			μA
	Output Voltage Deviation	ΔVo	V _{DD1} = 3.3 V, V _{DD2} = 8.5 V,		±7	±20	mV
	Output Swing Difference	ΔV_{P-P}	Vout = 2.0 V, 4.25 V, 6.5 V,		±2	±30	mV
	Deviation		T _A = 25°C				
	Logic Part Dynamic Current	IDD1	VDD1		3.2	6.0	mA
	Consumption						
	Driver Part Dynamic Current	IDD2	VDD2, with no load		4.6	7.0	mA
	Consumption						

Electrical Characteristics (TA = -10 to +75°C, VDD1 = 2.5 to 3.6 V, VDD2 = 8.5 V ± 0.5 V, VSS1 = VSS2 = 0 V)

Note Vx refers to the output voltage of analog output pins S1 to S384.

VOUT refers to the voltage applied to analog output pins S1 to S384.

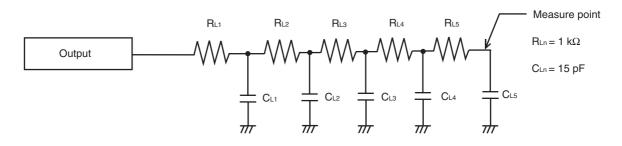
Cautions 1. fstb = 65 kHz, fclk = 54 MHz

- 2. The TYP. values refer to an all black or all white input pattern. The MAX. value refers to the measured values in the dot checkerboard input pattern.
- 3. Refers to the current consumption per driver when cascades are connected under the assumption of XGA single-sided mounting (10 units).

Switching Characteristics (TA = -10 to +75°C, VDD1 = 2.5 to 3.6 V, VDD2 = 8.5 V ± 0.5 V, Vss1 = Vss2 = 0 V)

		, , ,		,		,
Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Start Pulse Delay Time	t PLH1	CL = 15 pF, VDD1 = 2.5 to 3.6 V		10	17	ns
		C _L = 15 pF, V _{DD1} = 3.0 to 3.6 V		8	10.5	ns
Driver Output Delay Time	tPLH2	CL = 75 pF, RL = 5 kΩ			(2.5)	μs
	t PLH3				(4)	μs
	tPHL2				(2.5)	μs
	t _{PHL3}				(4)	μs
Input Capacitance	CI1	Exclude STHR (STHL), T _A = 25°C			10	pF
	CI2	STHR (STHL),TA = 25°C			15	pF

★ <Measurement Condition>



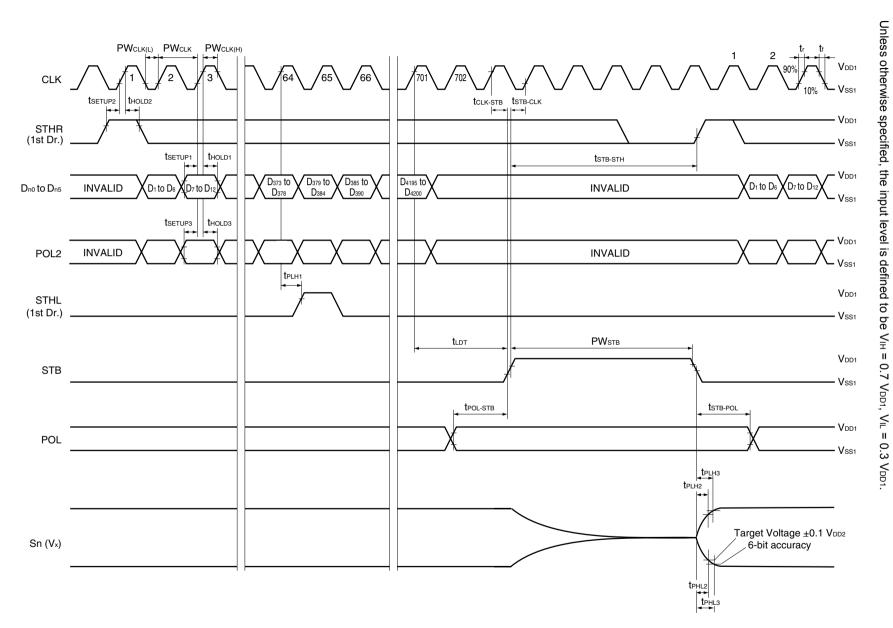
Timing Requirements (T_A = -10 to $+75^{\circ}$ C, V_{DD1} = 2.5 to 3.6 V, V_{SS1} = 0 V, t_r = t_f = 5.0 ns)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Clock Pulse Width	PWCLK		18			ns
Clock Pulse High Period	PWCLK(H)		4			ns
Clock Pulse Low Period	PWCLK(L)	$2.5 \text{ V} \leq \text{V}_{\text{DD1}} < 3.0 \text{ V}$	6			ns
		$3.0~V \leq V_{\text{DD1}} \leq 3.6~V$	4			ns
Data Setup Time	tsetup1		2			ns
Data Hold Time	t HOLD1		2			ns
Start Pulse Setup Time	tsetup2		2			ns
Start Pulse Hold Time	thold2		2			ns
POL21/22 Setup Time	tsetup3		2			ns
POL21/22 Hold Time	t HOLD3		2			ns
STB Pulse Width	PW STB		3		111	CLK
Last Data Timing	t ldt		2			CLK
CLK-STB Time	tclk-stb	$CLK \uparrow \to STB \uparrow$	6			ns
STB-CLK Time	tstb-clk	$STB \uparrow \to CLK \uparrow$	9			ns
Time Between STB and Start Pulse	t sтв-sтн	$STB \uparrow \to STHR(STHL) \uparrow$	2			CLK
POL-STB Time	t POL-STB	POL \uparrow or $\downarrow \rightarrow$ STB \uparrow	-5			ns
STB-POL Time	tstb-pol	$STB \downarrow \to POL \downarrow or \uparrow$	6			ns

Remark Unless otherwise specified, the input level is defined to be $V_{IH} = 0.7 V_{DD1}$, $V_{IL} = 0.3 V_{DD1}$.







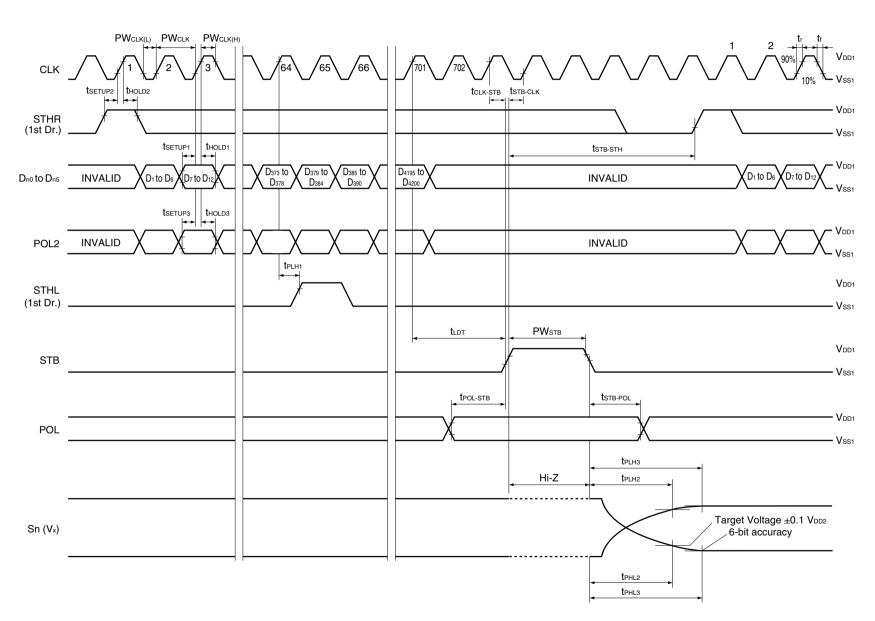
Data Sheet S15375EJ1V0DS





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★ 11. RECOMMENDED MOUNTING CONDITIONS

The following conditions must be met for mounting conditions of the μ PD16717.

For more details, refer to the Semiconductor Device Mounting Technology Manual (C10535E).

Please consult with our sales offices in case other mounting process is used, or in case the mounting is done under different conditions.

µPD16717N-xxx : TCP (TAB Package)

Mounting Condition	Mounting Method	Condition
Thermocompression	Soldering	Heating tool 300 to 350°C, heating for 2 to 3 seconds : pressure 100g
		(per solder)
	ACF	Temporary bonding 70 to 100°C : pressure 3 to 8 kg/cm ² : time 3 to 5
	(Adhesive	sec. Real bonding 165 to 180°C: pressure 25 to 45 kg/cm ² : time 30 to
	Conductive Film)	40 sec. (When using the anisotropy conductive film SUMIZAC1003 of
		Sumitomo Bakelite,Ltd).

Caution To find out the detailed conditions for mounting the ACF part, please contact the ACF manufacturing company. Be sure to avoid using two or more mounting methods at a time.

NOTES FOR CMOS DEVICES

① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note:

Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

(2) HANDLING OF UNUSED INPUT PINS FOR CMOS

Note:

No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note:

Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

Reference Documents

NEC Semiconductor Device Reliability/Quality Control System (C10983E) Quality Grades On NEC Semiconductor Devices (C11531E)

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